FEATURES

• Convenient, cost-effective means of converting DIP-to-SOIC PC board layouts.

GENERAL SPECIFICATIONS

• SOCKET BODY: black, UL 94V-0 glass-filled 4/6 Nylon 170°C continuous use temp
• PCB: FR-4, 0.062 [1.58] thick
• MALE ADAPTER PIN: Brass 360 1/2-hard per UNS C36000, ASTM B16/B16M
• MALE PIN PLATING: 200µ [5.08µ] Sn/Pb 93/7 per ASTM B579-73 over 100µ [2.54µ] Ni per SAE AMS-QQ-N-290
• FEMALE CONTACT PIN: Brass 360 1/2-hard per UNS C36000, ASTM B16/ B16M
• FEMALE PIN PLATING: 10µ [0.254µ] Au per MIL-G-45204 over 100µ [2.54µ] Ni per SAE AMS-QQ-N-290
• 4-FINGER COLLET CONTACT: BeCu per UNS C17200, ASTM B194-08
• FEMALE CONTACT PLATING: 10µ [0.254µ] Au per MIL-G-45204 over 50µ [1.27µ] Ni per SAE AMS-QQ-N-290
• CONTACT CURRENT RATING: 3 amps
• OPERATING TEMPERATURE: 221°F [105°C]
• INSERTION FORCE: 180g/pin; based on a 0.018 [0.46] dia. test lead
• WITHDRAWAL FORCE: 90g/pin; based on a 0.018 [0.46] dia. test lead
• NORMAL FORCE: 140g/pin; based on a 0.018 [0.46] dia. test lead
• SOCKET ACCEPTS LEADS: 0.015-0.025 [0.38-0.64] in dia., 0.100-0.125 [2.54-3.18] long

MOUNTING CONSIDERATIONS

• SUGGESTED PCB SOLDER PAD SIZE: 0.028 [0.71] min. width

ALL DIMENSIONS: INCHES [MILLIMETERS]

ALL TOLERANCES: ±0.005 [0.13] UNLESS OTHERWISE SPECIFIED

CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS

ORDERING INFORMATION

XX-354000-X 0

P/N Suffix Dim. “X” Dim. “Y”
-10 0.265 [16.73] 0.050 [1.27]
-20 0.325 [8.26] 0.110 [2.79]